

MiniSKiiP® 2 Dual

Half-Bridge

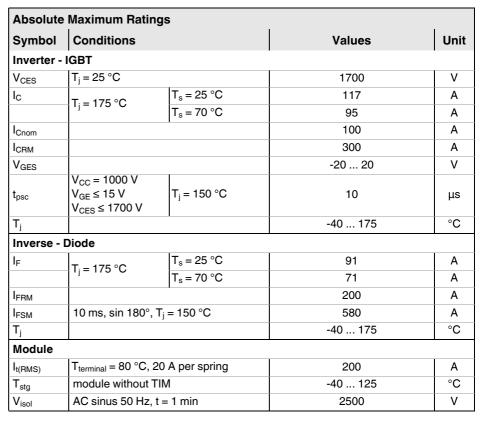
SKiiP 22GB17E4V1

Features*

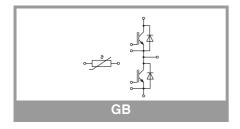
- Trench IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532
- NTC T-Sensor

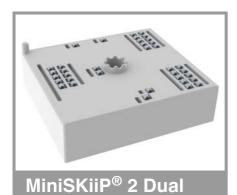
Remarks

- Max. case temperature limited to T_C=125°C
- Product reliability results valid for T_j≤150°C (recommended T_{j,op}=-40...+150°C)
- The creepage distance between T-Sensor and ground is 8mm



Characteristics									
Symbol	Conditions		min.	typ.	max.	Unit			
Inverter -	IGBT								
V _{CE(sat)}	I _C = 100 A	T _j = 25 °C		1.90	2.20	V			
	V _{GE} = 15 V chiplevel	T _j = 150 °C		2.30	2.60	V			
V_{CE0}	chiplevel	T _j = 25 °C		0.80	0.90	V			
	Chipievei	T _j = 150 °C		0.70	0.80	V			
r _{CE}	V _{GE} = 15 V chiplevel	T _j = 25 °C		11	13	mΩ			
		T _j = 150 °C		16	18	mΩ			
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 4 \text{ m}$	A	5.2	5.8	6.4	V			
I _{CES}	V _{GE} = 0 V V _{CE} = 1700 V	T _j = 25 °C			0.3	mA			
				-		mA			
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		8.00		nF			
Coes		f = 1 MHz		0.34		nF			
C _{res}	VGE - O V	f = 1 MHz		0.29		nF			
Q_{G}	- 8 V+ 15 V			800		nC			
R _{Gint}	T _j = 25 °C			7.5		Ω			
t _{d(on)}	V _{CC} = 900 V			232		ns			
t _r	I _C = 100 A			41		ns			
Eon	$R_{G \text{ on}} = 2 \Omega$ $R_{G \text{ off}} = 2 \Omega$			22.2		mJ			
t _{d(off)}	$di/dt_{on} = 2892 \text{ A/}\mu\text{s}$			600		ns			
t _f	di/dt _{off} = 665 A/μs			144		ns			
E _{off}	dv/dt = 5490 V/ μ s V _{GE} = +15/-15 V L _s = 25 nH			30.7		mJ			
$R_{th(j-s)}$	per IGBT, λ _{paste} =0.8	3 W/(K*m)		0.43		K/W			





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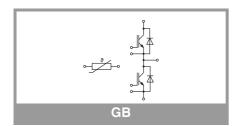
Features*

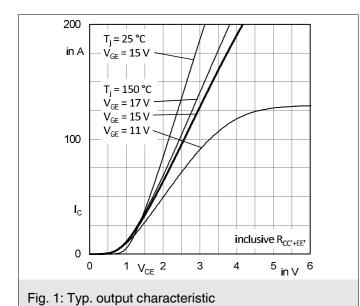
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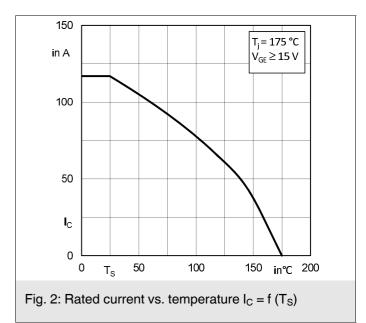
Remarks

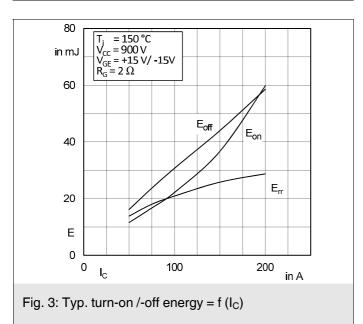
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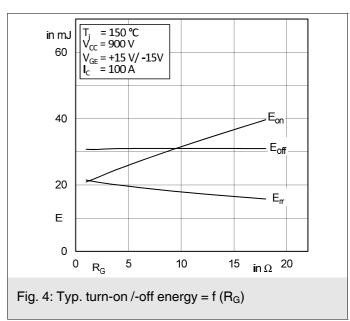
Characteristics							
Symbol	Conditions		min.	typ.	max.	Unit	
Inverse - Diode							
$V_F = V_{EC}$	I _F = 100 A	T _j = 25 °C		2.00	2.40	V	
	V _{GE} = 0 V chiplevel	T _j = 150 °C		2.15	2.57	V	
V_{F0}	chiplevel	T _j = 25 °C		1.32	1.56	V	
	Criipievei	T _j = 150 °C		1.08	1.22	V	
r _F	_! chinlevel	T _j = 25 °C		6.8	8.4	mΩ	
		T _j = 150 °C		11	14	mΩ	
I _{RRM}	I _F = 100 A			165		Α	
Q _{rr}	di/dt _{off} = 3753 A/μs V _{GE} = -15 V			32.5		μC	
E _{rr}	$V_{CC} = 900 \text{ V}$			20.9		mJ	
R _{th(j-s)}	per Diode, λ _{paste} =0.8 W/(K*m)		0.7			K/W	
Module							
L _{CE}				20		nH	
Ms	to heat sink		2		2.5	Nm	
W		_		50		g	
Temperature Sensor							
R ₁₀₀	T _c =100°C (R ₂₅ =5 kΩ)			Ω			
B _{25/85}	$R_{(T)}=R_{25}*exp[B_{25/85}*(1/T-1/298)], T[K]$		3420			K	

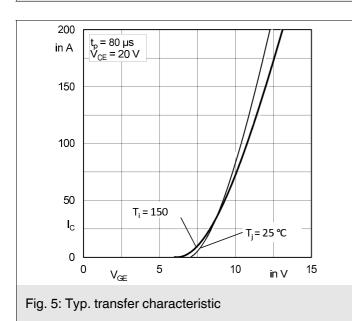


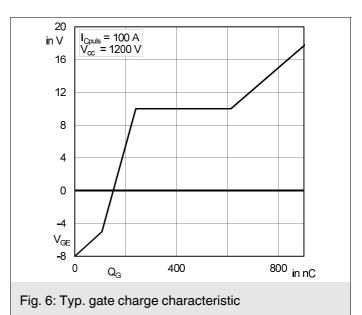


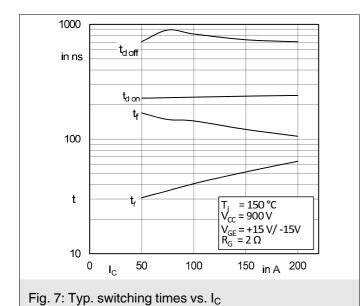


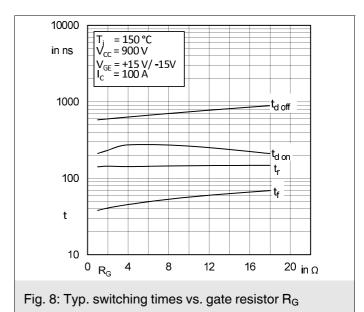


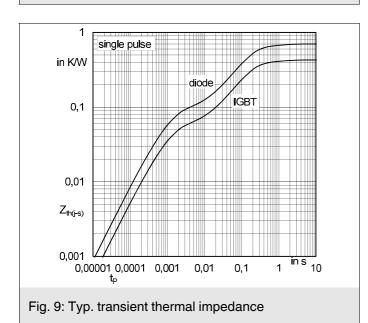


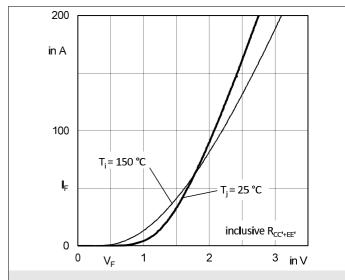


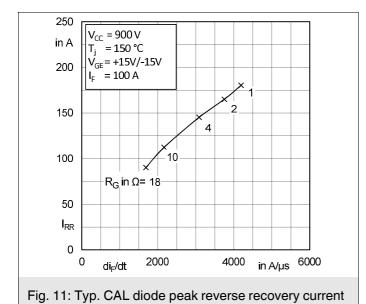


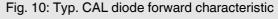












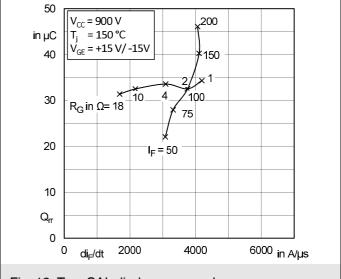
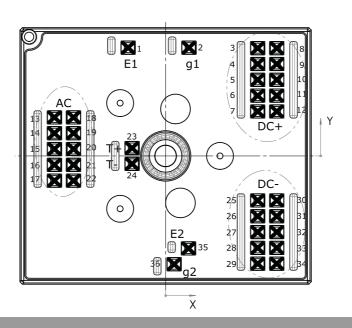


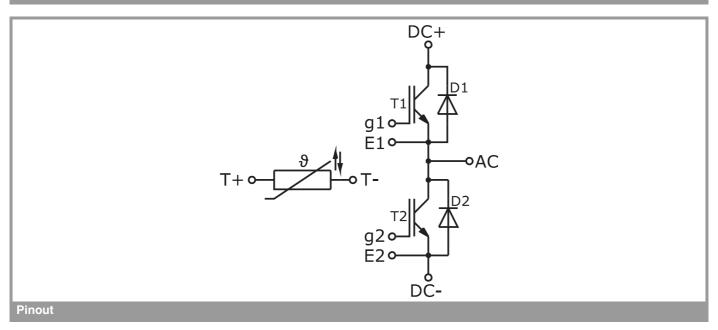
Fig. 12: Typ. CAL diode recovery charge

Pin out							
Pin	Χ	Υ	Function	Pin	X	Υ	Function
1	-7,58	21,9	E1	19	-18,63	4,6	AC
2	4,73	21,9	g1	20	-18,63	1,4	AC
3	18,63	21,8	DC+	21	-18,63	-1,8	AC
4	18,63	18,6	DC+	22	-18,63	-5	AC
5	18,63	15,4	DC+	23	-6,78	1,6	T+
6	18,63	12,2	DC+	24	-6,78	-1,6	T-
7	18,63	9	DC+	25	18,63	-9	DC-
8	22,48	21,8	DC+	26	18,63	-12,2	DC-
9	22,48	18,6	DC+	27	18,63	-15,4	DC-
10	22,48	15,4	DC+	28	18,63	-18,6	DC-
11	22,48	12,2	DC+	29	18,63	-21,8	DC-
12	22,48	9	DC+	30	22,48	-9	DC-
13	-22,48	7,8	AC	31	22,48	-12,2	DC-
14	-22,48	4,6	AC	32	22,48	-15,4	DC-
15	-22,48	1,4	AC	33	22,48	-18,6	DC-
16	-22,48	-1,8	AC	34	22,48	-21,8	DC-
17	-22,48	-5	AC	35	4,63	-18,7	E2
18	-18,63	7,8	AC	36	1,73	-21,9	g2

all values in [mm]



Pinout and Dimensions



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

*IMPORTANT INFORMATION AND WARNINGS

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